



F40-P

AIR-BORNE IP66 MISSION COMPUTER



- IP66 Military Air Borne Mission Computer
- Intel 12th Gen Alder Lake P, i7-1265UE(10xC), 4.7GHz
- Frame Grabber : 4xCH HD-SDI
- 3xDVI, 2xLAN, 2xUSB3.0, 3xCOM
- 1 x 2.5" Swappable SATA Drive
- MIL-STD 18V~36V EMI DC Input , Options for MIL-STD-704/ 461/ 1275 10V~40V DC
- Extreme Temperature -40~+60 degree
- MIL-STD 810 509 Salt Fog (Conformal Coating)
- MIL-STD 810 500.5 Low Pressure (50,000 ft) Altitude

Specifications

System

CPU	Intel® Core™ i, i7-1265UE (SoC) ,15W, 10 Core, 4.7GHz
Memory type	2 x DDR5 SODIMM up to 64GB
Chipset	Intel® SoC Integrated
Graphic	Intel® Iris Xe Graphics
BIOS	AMI UEFI BIOS
TPM	Nuvoton NPCT750AABYX TPM2.0
Power Type	18V~36V EMI DC Input , Options for 10V~36V DC- IN
Storage	1 x 2.5" Swappable SATA SSD Tray
Operating Temperature	-40° to +60° C
Dimension	5.29 inch(H) x 6.97 inch(W) x 11.3 inch(L)

Front I/O

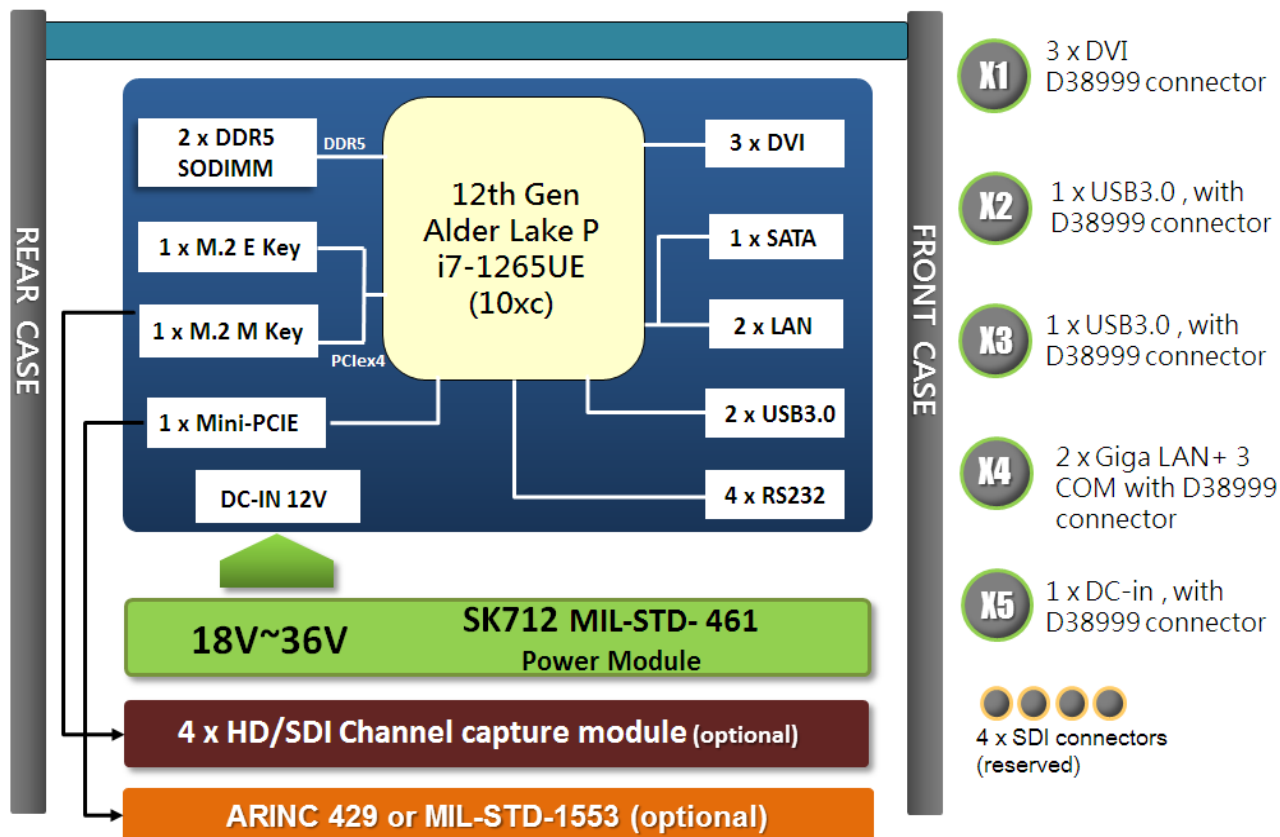
X1	3 x DVI with 100 PIN D38999 connector
X2	1 x USB3.0 with USB3.0 D38999 connector
X3	1 x USB3.0 with USB3.0 D38999 connector
X4	2 x LAN +3 x COM with 50PIN D38999 connector
X5	1 x DC IN with D38999 connector
Others	1 x 2.5" Easy swap HDD/SSD Tray 4 x SDI connectors 1 x Power button 1 x Reset button

Environmental

MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L
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	Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)
Reliability	No Moving Parts; Passive Cooling. Designed & Manufactured using ISO 9001 Certified Quality Program.
MIL-STD-461	CE102 basic curve, 10kHz - 30 MHz RE102-4, (1.5 MHz) -30 MHz - 5 GHz RS103, 200 MHz - 3.2 GHz, 50 V/m equal for all frequencies EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV EN 61000-4-3: 10V/m EN 61000-4-4: Signal and DC-Net: 1 kV EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV CE and FCC
MIL-STD-1275	Steady State – 20V~33V, Surge Low – 18V/500ms, Surge High – 100V/500ms Emitted spikes Injected Voltage surges Emitted voltage surges Voltage ripple (2V) Voltage spikes Starting Operation Reverse polarity
MIL-STD-704	Load Measurements (LDC101) Steady State Limits for Voltage (LDC102) Voltage Distortion Spectrum (LDC103) Total Ripple (LDC104) Normal Voltage Transients (LDC105) Power Interrupt (LDC201) Abnormal Steady State Limits for Voltage (LDC301) Abnormal Voltage Transients (LDC302) Emergency Steady State Limits for Voltage (LDC401) Starting Voltage Transients (LDC501) Power Failure (LDC601) Phase Reversal (LDC602)
Operating Temp.	-40 to +60°C (ambient with air flow)
Storage Temp.	-40 to +85°C
Relative Humidity	5% to 95%, non-condensing.

Block Diagram



Appearance & Dimension

